

CLAIM AMENDMENTS

1. (Currently Amended) An integrated circuit device, comprising ~~characterized in that it comprises:~~

[[-]] an active chip of a semiconductor material comprising an electrical circuit, the active chip having an active face provided with a plurality of electrical connection terminals and a second face, wherein the chip has a thickness of less than 100 pm, and

[[-]] a complementary chip having a first face attached to the active face of the active chip, a second face and a side surface, wherein the complementary chip has a plurality of recesses, each recess extending through the whole thickness of the complementary chip and extending from above a contact terminal to said side surface, the complementary chip having a larger thickness than the active chip, wherein each recess extends laterally inward from a perimeter of the complimentary chip.

2. (Currently Amended) [[An]] The integrated circuit device of according to ~~claim 1, characterized in that~~ wherein the thickness of the active layer ranges from 5 to 50 pm.

3. (Currently Amended) [[An]] The integrated circuit device of according to ~~claim 2, characterized in that~~ wherein the thickness of the complementary layer ranges from 100 to 200 pm.

4. (Currently Amended) [[An]] The integrated circuit device according to any of claims 1 to 3, wherein ~~characterized in that~~ the complementary chip is formed with the same semiconductor material as the active chip.

5. (Currently Amended) An electronic unit for smart cards, comprising ~~characterized in that it comprises:~~

[[-]] an active chip of a semiconductor material comprising an electrical circuit, the active chip having an active face provided with a plurality of electrical connection terminals and a second face, wherein the chip has a thickness of less than 100 pm,

[[-]] a complementary chip having a first face attached to the active face of the active chip, a second face and a side surface, wherein the complementary chip has a

plurality of recesses, each recess extending through the whole thickness of the complementary chip and extending from above a contact terminal to said side surface, the complementary chip having a larger thickness than the active chip, wherein each recess extends laterally inward from a perimeter of the complimentary chip.

[[-]] an insulating substrate having an outer face provided with outer electrical contact pads and an inner face, the second face of the active chip being attached to the substrate inner face, and

[[-]] a plurality of electrical leads, each lead having a first end connected to a contact terminal and a second end connected to an outer contact pad and lying entirely between the plane containing the second face of the complementary chip and the insulating substrate.

6. (Currently Amended) [[An]] The electronic unit of according to claim 5, ~~characterized in that~~ wherein the insulating substrate includes windows, each window being disposed above an outer electric contact pad.
7. (Original) A smart card comprising an electronic unit according to claim 5.
8. (Cancelled)